# Bi-directional TVS Array for High-Speed Data Line Protection

The SMDA05C transient voltage suppressor series is designed to protect equipment attached to up to four high speed communication lines from ESD, EFT, and lightning.

#### Features:

- SO-8 Package
- Peak Power 300 W 8 x 20 μS
- ESD Rating:

IEC 61000-4-2 (ESD) ±15 kV (air) ±8 kV (contact)

IEC 61000-4-4 (EFT) 40 A (5/50 ns)

IEC 61000-4-5 (lightning) 12 A (8/20 μs)

- UL Flammability Rating of 94 V-0
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

# **Typical Applications:**

- High Speed Communication Line Protection
- Data and I/O Lines
- Microprocessor Based Equipment
- LAN/WAN Equipment
- Servers
- Notebook and Desktop PC
- Serial and Parallel Ports
- Peripherals

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Power Dissipation 8 x 20 μs @ T <sub>A</sub> = 25°C (Note 1)	P <sub>pk</sub>	300	W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature – Maximum 10 Seconds Duration	TL	260	°C

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1. Non-repetitive current pulse 8 x 20  $\mu S$  exponential decay waveform

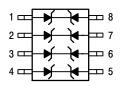


# ON Semiconductor®

http://onsemi.com

# SO-8 VOLTAGE SUPPRESSOR 300 WATTS PEAK POWER

# PIN CONFIGURATION AND SCHEMATIC





SO-8 CASE 751

## **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

## ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 3 of this data sheet.

# SMDA05C ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	-	-	5.0	V
Reverse Breakdown Voltage @ I <sub>t</sub> = 1.0 mA	V <sub>BR</sub>	6.0	-	-	V
Reverse Leakage Current @ V <sub>RWM</sub> = 5 Volts	I <sub>R</sub>	N/A	-	20	μΑ
Maximum Clamping Voltage @ I <sub>PP</sub> = 1.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	9.8	V
Maximum Clamping Voltage @ I <sub>PP</sub> = 5.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	11	V
Maximum Peak Pulse Current, 8 x 20 μs	I <sub>PP</sub>	-	-	17	Α
Junction Capacitance @ V <sub>R</sub> = 0 V, f = 1 MHz	CJ	-	-	350	pF

# **SMDA12C ELECTRICAL CHARACTERISTICS**

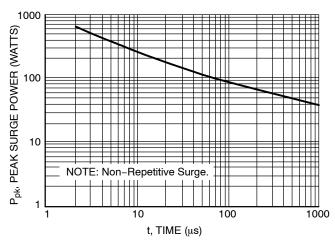
Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	-	-	12	V
Reverse Breakdown Voltage @ I <sub>t</sub> = 1.0 mA	V <sub>BR</sub>	13.3	-	-	V
Reverse Leakage Current @ V <sub>RWM</sub> = 12 Volts	I <sub>R</sub>	N/A	-	1.0	μΑ
Maximum Clamping Voltage @ I <sub>PP</sub> = 1.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	19	V
Maximum Clamping Voltage @ I <sub>PP</sub> = 5.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	24	V
Maximum Peak Pulse Current, 8 x 20 μs	I <sub>PP</sub>	_	-	12	Α
Junction Capacitance @ V <sub>R</sub> = 0 V, f = 1 MHz	CJ	-	_	120	pF

# **SMDA15C ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	-	-	15	V
Reverse Breakdown Voltage @ I <sub>t</sub> = 1.0 mA	V <sub>BR</sub>	16.7	-	-	V
Reverse Leakage Current @ V <sub>RWM</sub> = 15 Volts	I <sub>R</sub>	N/A	-	1.0	μΑ
Maximum Clamping Voltage @ I <sub>PP</sub> = 1.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	24	V
Maximum Clamping Voltage @ I <sub>PP</sub> = 5.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	30	V
Maximum Peak Pulse Current, 8 x 20 μs	I <sub>PP</sub>	-	-	10	Α
Junction Capacitance @ V <sub>R</sub> = 0 V, f = 1 MHz	CJ	-	-	75	pF

# SMDA24C ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Working Voltage	V <sub>RWM</sub>	-	-	24	V
Reverse Breakdown Voltage @ I <sub>t</sub> = 1.0 mA	V <sub>BR</sub>	26.7	-	-	V
Reverse Leakage Current @ V <sub>RWM</sub> = 24 Volts	I <sub>R</sub>	N/A	-	1.0	μА
Maximum Clamping Voltage @ I <sub>PP</sub> = 1.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	43	V
Maximum Clamping Voltage @ I <sub>PP</sub> = 5.0 A, 8 x 20 μs	V <sub>C</sub>	N/A	-	55	V
Maximum Peak Pulse Current, 8 x 20 μs	I <sub>PP</sub>	-	-	5.0	Α
Junction Capacitance @ V <sub>R</sub> = 0 V, f = 1 MHz	CJ	_	-	50	pF



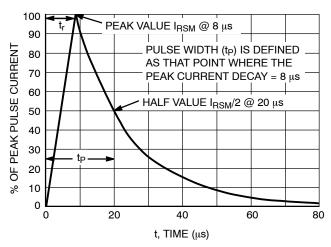


Figure 1. Pulse Width

Figure 2.  $8 \times 20 \mu s$  Pulse Waveform

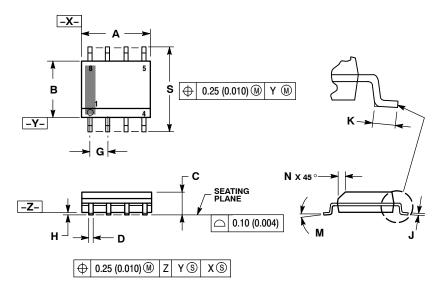
#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
SMDA05CDR2G	AAA	SO-8 (Pb-Free)	2500 / Tape & Reel
SMDA12CDR2G	AAC	SO-8 (Pb-Free)	2500 / Tape & Reel
SMDA15CDR2G	AAD	SO-8 (Pb-Free)	2500 / Tape & Reel
SMDA24CDR2G	AAE	SO-8 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

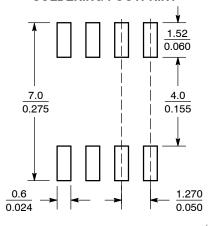
#### SOIC-8 NB CASE 751-07 **ISSUE AK**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

#### SOLDERING FOOTPRINT\*



(mm) SCALE 6:1

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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